

APPROVAL SHEET

MULTILAYER CERAMIC CAPACITORS

Microwave Capacitors Series (RT)

Qualified to AEC-Q200

0402 Size (25V to 50V)

NP0 Dielectric

Halogen Free & RoHS Compliance

*Contents in this sheet are subject to change without prior notice.



1. DESCRIPTION

MLCC consists of a conducting material and electrodes. To manufacture a chip-type SMT and achieve miniaturization, high density and high efficiency, ceramic condensers are used.

WTC's RT series MLCC is used at high frequencies generally have a small temperature coefficient of capacitance, typical within the ±30ppm/°C required for NP0 (C0G) classification and have excellent conductivity internal electrode. Thus, WTC RT series MLCC will be with the feature of low ESR and high Q characteristics, stability and reliability. Besides, RT series MLCC is tighten controlling in quality in line to assure quality performance in automotive applications. The RT series is AEC-Q200 compliant.

2. FEATURES

- a. High Q and low ESR performance at high frequency.
- b. High reliability: AEC-Q200.
- c. Ultra low capacitance to 0.1pF.
- d. Can offer high precision tolerance to ±0.05pF.
- e. Quality improvement of telephone calls for low power loss and better performance.

3. APPLICATIONS

- Automotive, power supply and related industries. .
- The other mechanical stress concerned products or the set having a high probability of fall.
- Prevention of ceramic body cracks by board bending.
- RF module: Power amplifier, VCO. d.
- Tuners.

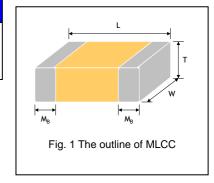
4. HOW TO ORDER

<u>15</u>	<u>N</u>	<u>101</u>	<u>J</u>	<u>250</u>	<u>C</u>	I
Size	Dielectric	Capacitance	Tolerance	Rated voltage	<u>Termination</u>	Packaging style
15 =0402 1005)		Two significant digits followed by no. of zeros. And R is in place of decimal point. eg.: 0R5=0.5pF 1R0=1.0pF 100=10x10 ¹	A=±0.05pF B=±0.1pF C=±0.25pF D=±0.5pF F=±1% G=±2% J=±5%	ANCE		T=7" reeled G=13" reeled
	<u>6ize</u> 5 =0402	Dielectric 5 =0402 N =NP0 1005)	5=0402 1005) N=NP0 Two significant digits followed by no. of zeros. And R is in place of decimal point. eg.: 0R5=0.5pF 1R0=1.0pF		SizeDielectricCapacitanceToleranceRated voltage 5 =0402 1005)N=NP0Two significant digits followed by no. of zeros. And R is in place of decimal point. \mathbf{A} =±0.05pF \mathbf{B} =±0.1pF \mathbf{C} =±0.25pF \mathbf{D} =±0.5pF \mathbf{F} =±1% \mathbf{G} =±2% \mathbf{J} =±5%Two significant digits followed by no. of zeros. And R is in place of decimal point. \mathbf{G} =±2% \mathbf{J} =±5%250=25 VDC 500=50 VDC	Size Dielectric Capacitance Tolerance Rated voltage Termination 5=0402 (1005) N=NP0 Two significant digits followed by no. of zeros. And R is in place of decimal point. A=±0.05pF (B=±0.1pF) Two significant digits followed by no. of zeros. And R is in place of decimal point. C=±0.25pF (D=±0.5pF) And R is in place of decimal point. 6=±2% (DR5=0.5pF) 1R0=1.0pF (100=10x10¹) 250=25 VDC 500=50 VDC

5. EXTERNAL DIMENSIONS

Size Inch (mm)	L (mm)	W (mm)	T (mm)/Symb	ol	Remark	M _B (mm)
0402 (1005)	1.00±0.08	0.50±0.08	0.50±0.08	N	#	0.25 +0.05/-0.10

[#] Reflow soldering only is recommended.



6. GENERAL ELECTRICAL DATA

Dielectric	NP0			
Size	402			
Capacitance*	0.1pF to 56pF			
Capacitance tolerance	Cap≤5pF ^{#1} : A (±0.05pF), B (±0.1pF), C (±0.25pF) 5pF <cap<10pf: (±0.1pf),="" (±0.25pf),="" (±0.5pf)="" (±1%),="" (±2%),="" (±5%)<="" b="" c="" cap≥10pf:="" d="" f="" g="" j="" th=""></cap<10pf:>			
Rated voltage (WVDC)	25V, 50V			
Q*	Cap<30pF:Q≥400+20C; Cap≥30pF:Q≥1000			
Insulation resistance at Ur	≥10GΩ or RxC≥100Ω-F whichever is smaller.			
Operating temperature	-55 to +125℃			
Capacitance change	±30ppm/℃			
Termination	Ni/Sn (lead-free termination)			

^{#1:} Cap= 0.1pF product only provide B tolerance.

Apply 1.0±0.2Vrms, 1.0MHz±10% for Cap≤1000pF and 1.0±0.2Vrms, 1.0kHz±10% for Cap>1000pF.



 $^{^{\}star}$ Measured at the conditions of 25°C ambient temper ature and 30~70% related humidity.

7. CAPACITANCE RANGE

	DIELECTRIC		NI	20	
	SIZE		04		
R	ATED VOLTAGE (VDC	`	25	50	Tolerance
	0.1pF (0		N N	N	В
	0.2pF (0)R2)	N	N	A, B
	0.3pF (0		N	N	A, B
	0.4pF (0		N N	N	A, B
	0.5pF (0 0.6pF (0		N N	N N	A, B, C A, B, C
	0.7pF (0)R7)	N N	N N	A, B, C
	0.75pF (F		N	N	A, B, C
	0.8pF (0		N	N	A, B, C
	0.9pF (0		N	N	A, B, C
	1.0pF (1 1.1pF (1		N N	N N	A, B, C A, B, C
	1.2pF (1		N	N N	A, B, C
	1.3pF (1	R3)	N	N	A, B, C
	1.5pF (1	R5)	N	N	A, B, C
	1.6pF (1		N	N	A, B, C
	1.8pF (1 2.0pF (2		N N	N N	A, B, C A, B, C
	2.0pr (2 2.2pF (2		N N	N N	A, B, C
	2.4pF (2	2R4)	N	N	A, B, C
	2.7pF (2	2R7)	N	N	A, B, C
	3.0pF (3	R0)	N	N	A, B, C
	3.3pF (3		N N	A N	A, B, C
	3.6pF (3 3.9pF (3		N/, N/	NZ (Z N)	A, B, C A, B, C
	4.0pF (4		N - S	版历 系。	A, B, C
	4.3pF (4		3 N	N/N	A, B, C
	4.7pF (4		717 N 43	N	A, B, C
	5.0pF (5		N-HH	N	A, B, C
	5.1pF (5 5.6pF (5	R1)	N'TH'	N N	B, C, D B, C, D
မွ	6.0pF (6		N PASSIVE	SYSTEM ALL NANCE	B, C, D
Capacitance	6.2pF (6		SNA PASSIVE	N S	B, C, D
aci	6.7pF (6		No.	N .9 8	B, C, D
Зар	6.8pF (6		N	N	B, C, D
U	7.0pF (7 7.5pF (7	(RU)	N N	N N	B, C, D B, C, D
	8.0pF (8	R0)	N/I/o Ch	N	B, C, D
	8.2pF (8	R2)	N 9/1/7	TOIOS N	B, C, D
	9.0pF (9		N CCHIN	OCY CODDOD MUN.	B, C, D
	9.1pF (9		N N	OGY COKPONN.	B, C, D
	10pF (1 11pF (1		N N	N N	F, G, J F, G, J
	12pF (1		N N	N	F, G, J
	13pF (1	130)	N	N	F, G, J
	15pF (1		N	N	F, G, J
	16pF (1		N N	N N	F, G, J
	18pF (1 20pF (2		N N	N N	F, G, J F, G, J
	22pF (2		N	N	F, G, J
	24pF (2	2 40)	N	N	F, G, J
	27pF (2		N	N	F, G, J
	30pF (3		N N	N N	F, G, J F, G, J
	33pF (3		N N	N N	F, G, J F, G, J
	39pF (3		N	N	F, G, J
	43pF (4	430)	N	N	F, G, J
	47pF (4		N	N	F, G, J
	51pF (5 56pF (5	560\	N N		F, G, J F, G, J
	62pF (6		IV		F, G, J
	68pF (6	(086			
	75pF (7	750)			
	82pF (8				
	91pF (9 100pF (1				
			the symbol of product thicknes		<u> </u>

^{1.} The letter in cell is expressed the symbol of product thickness.

^{2.} For more information about products with special capacitance or other data, please contact WTC local representative



8. PACKAGING STYLE AND QUANTITY

Size	Circ Thislman (mm)(Combal		Paper tape		
Size	Thickness (mm)/Sy	/IIIDOI	7" reel	13" reel	
0402 (1005)	0.50±0.08	N	10,000	50,000	

Unit: pieces



served.



9. RELIABILITY TEST CONDITIONS AND REQUIREMENTS

No.	AEC-Q200 Test Item	AEC-Q200 Test Condition	Requirements		
1.	Pre-and Post-Stress Electrical Test				
2.	High Temperature Exposure (Storage) MIL-STD-202 Method 108	* Test temp.: 150±3℃ * Unpowered. * Test time: 1000+24/-0 hrs. * Measurement to be made after keeping at room temp. for 24±2 hrs.	* No remarkable damage. * Cap change: NPO: within ±2.5% or ±0.25pF whichever is larger. * Q. value: NPO: Cap≥30pF, Q≥1000; Cap<30pF, Q≥400+20C. * I.R.: ≥10GΩ or RxC≥500Ω-F whichever is smaller.		
3.	Temperature Cycling JESD22 Method JA-104	* Conduct 1000 cycles according to the temperatures and time. Step Temp. (°C) Time (min.) 1 -55°C +0/-3 5±1 2 +125°C +3/-0 5±1 *Measurement to be made after keeping at room temp. for 24±2 hrs.	s * No remarkable damage. * Cap change : NPO: within ±2.5% or 0.25pF whichever is larger. * Q. value: NPO: Cap≥30pF, Q≥1000 ; Cap<30pF, Q≥400+20C. * I.R.: ≥10GΩ or RxC≥500Ω-F whichever is smaller.		
4.	Destructive Physical Analysis EIA-469	Per EIA-469	No defects or abnormalities		
5.	Moisture Resistance MIL-STD-202 Method 106	* Test temp.: 25~65°C * Humidity: 80~100% RH * Test time: 10 cycles, t=24hrs/cycle. * Measurement to be made after keeping at room temp. for 24±2 hrs.	* No remarkable damage. * Cap change : NPO: within ±3.0% or 0.30pF whichever is larger * Q. value: NPO: More than 30pF Q≥350 ; 10pF≤C≤30pF, Q≥275+2.5C Less than 10pF Q≥200+10C * I.R.: ≥10GΩ or RxC≥500Ω-F whichever is smaller.		
6.	Biased Humidity MIL-STD-202 Method 103	* Test temp.: 85±3°C * Humidity: 85%RH * Test time: 1000+24/-0 hrs. * To apply voltage: rated voltage and 1.3~1.5Vdc. (add 100k ohm resistor) * Measurement to be made after keeping at room temp. for 24±2 hrs.	* No remarkable damage. * Cap change: NPO: within ±3.0% or 0.30pF whichever is larger. * Q. value: NPO: C≥30pF, Q≥200; C<30pF, Q≥100+10/3C * I.R.: ≥1GΩ or RxC≥50Ω-F whichever is smaller.		
7.	Operational Life MIL-STD-202 Method 108	* No remarkable damage. To apply voltage: full rated voltage. * Cap change: NPO: within ±3.0% or ±0.3pF whichever is larger * Cap change: NPO: within ±3.0% or ±0.3pF whichever is larger * Q. value: NPO: More than 30pF, Q≥350; 10pF≤C<30pF, Q≥275+3 * Q. value: NPO: More than 10pF, Q≥200+10C * Less than 10pF, Q≥200+10C * LR.: ≥1GΩ or RxC≥50Ω-F whichever is smaller.			
8.	External Visual MIL-STD-883 Method 2009	Visual inspection	No remarkable defect.		
9.	Physical Dimension JESD22 Method JB-100	Using by calipers	Within the specified dimensions		

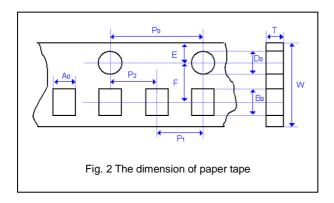
10. Resistance to Solvents * Temperature: 25±5℃ * No remarkable damage. MIL-STD-202 * Solvent: Iso-propyl alcohol. * Q. value: NPO: Cap≥30pF, Q≥1000; Cap<30 method 215 11. Mechanical Shock MIL-STD-202 * Peak value: 1500g's. * No remarkable damage. MIL-STD-202 * Wave: 1/2 sine. * Cap.: within the specified tolerance. Method 213 * Velocity: 15.4 ft/sec * Q. value: NPO: Cap≥30pF, Q≥1000; Cap<30	naller. 0pF, Q≥400+20C.
MIL-STD-202 * Solvent: Iso-propyl alcohol. * Q. value: NPO: Cap≥30pF, Q≥1000 ; Cap<30 Method 215 * I.R.: ≥10GΩ or RxC≥500Ω-F whichever is sm 11. Mechanical Shock MIL-STD-202 * Wave: 1/2 sine. * Cap.: within the specified tolerance.	naller. 0pF, Q≥400+20C.
Method 215 * I.R.: ≥10GΩ or RxC≥500Ω-F whichever is sm 11. Mechanical Shock * Peak value: 1500g's. * No remarkable damage. MIL-STD-202 * Wave: 1/2 sine. * Cap.: within the specified tolerance.	naller. 0pF, Q≥400+20C.
11. Mechanical Shock * Peak value: 1500g's. * No remarkable damage. MIL-STD-202 * Wave: 1/2 sine. * Cap.: within the specified tolerance.)pF, Q≥400+20C.
MIL-STD-202 * Wave: 1/2 sine. * Cap.: within the specified tolerance.	
! ' ' '	
Method 213 * Velocity: 15.4 ft/sec * Q. value: NPO: Cap≥30pF, Q≥1000 ; Cap<30	
i i i i i i i i i i i i i i i i i i i	aller.
* Three shocks in each direction should be applied * I.R.: ≥10GΩ or RxC≥500Ω-F whichever is sm	
along	
3 mutually perpendicular axes of the test specimen	
(18 shocks)	
12. Vibration * Vibration frequency: 10~2000 Hz/min. * No remarkable damage.	
MIL-STD-202 (5g's for 20 min) * Cap.: within the specified tolerance.	
Method 204 * Total amplitude: 1.5mm * Q. value: NPO:Cap≥30pF, Q≥1000 ; Cap<30p	pF, Q≥400+20C.
* 12 cycles each of 3 orientations (36 times)	aller.
13. Resistance to * Solder temperature: 270±5℃ * No remarkable damage.	
Soldering Heat * Dipping time: 10±1 sec * Cap change: NPO: within ±2.5% or 0.25pF w	hichever is larger
MIL-STD-202 * Measurement to be made after keeping at room * Q. value: NPO: Cap≥30pF, Q≥1000 ; Cap<30	pF, Q≥400+20C.
Method 210 temp. for 24±2 hrs. * I.R.: ≥10GΩ or RxC≥500Ω-F whichever is sm	aller.
Thermal Shock * Conduct 300 cycles according to the temperatures * No remarkable damage.	
MIL-STD-202 and time. * Cap change : NPO: within ±2.5% or 0.25pF v	=
Method 107 Step Temp. (℃) Time (min.) *Q. value: NPO: Cap≥30pF, Q≥1000 ; Cap<30)pF, Q≥400+20C.
1 -55℃ +0/-3 15±3 11.R.: ≥10GΩ or RxC≥500Ω-F whichever is sm	aller.
2 +125℃ +3/-0 15±3	
* Max. transfer time: 20 sec.	
* Measurement to be made after keeping at room	
temp. for 24±2 hrs.	
Per AEC-Q200-002 PASSIVE SYSTEM* No remarkable damage.	
AEC-Q200-002 * Cap.: within the specified tolerance.	
* Q. value: NPO: Cap≥30pF, Q≥1000 ; Cap<30	pF, Q≥400+20C.
* I.R.: ≥10GΩ or RxC≥500Ω-F whichever is sm	aller.
16. Solderability * Condition A All terminations shall exhibit a continuous solder	· ·
J-STD-002 Un-mounted chips 4hrs / 155°C*dry then completely defects from a minimum of 95% of the critical s	surface area of any individual
JESD22-B102E immersed for 5±0.5 sec in solder bath at 245±5°C. termination.	
* Condition B	
Un-mounted chips steam 8 hrs then completely	
immersed for 10±1sec in solder bath at 220+5/-0°C.	
* Condition C	
Un-mounted chips steam 8 hrs then completely	
immersed for 10±1 sec. in solder bath at 260+0/-5°C.	

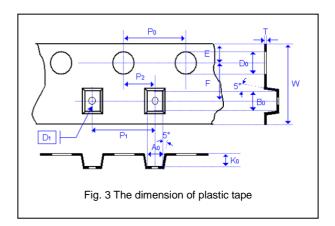
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Ma	AEC-Q200	AFC 0200 Test Conditions	Dominomonto.
No.	Test Item	AEC-Q200 Test Condition	Requirements
17.	Electrical	* Capacitance	* Capacitance within the specified tolerance.
	Characterization	* Q. value	* Q. value: NPO: Cap≥30pF, Q≥1000 ; Cap<30pF, Q≥400+20C.
		Cap≤1000pF 1.0±0.2Vrms, 1MHz±10%	
		Cap>1000pF 1.0±0.2Vrms, 1KHz±10%	
		* Insulation Resistance	* IR. ≥10GΩ or RxC≥500Ω-F whichever is smaller.
		To apply rated voltage(500V max.) for max. 120 sec.	
		* Dielectric Strength	* Dielectric strength
		To apply voltage:	No evidence of damage or flash over during test.
		≦100 ≥2.5 times VDC	
		, duration 1~5 sec,	
		charge and discharge current less than 50mA.	
		* Temperature Coefficient (with no electrical load)	* Temperature Coefficient
		Operation temperature: -55~125℃ at 25℃	Capacitance Change: NPO: Within ±30ppm/°C
18.	Board Flex	* The middle part of substrate shall be pressurized by	* No remarkable damage.
	AEC-Q200-005	means of the pressurizing rod at a rate of about 1	* Cap change: NPO: within ±5% or 0.5pF whichever is larger
		mm per second until the deflection becomes 5 mm	(This capacitance change means the change of capacitance under specified
		and then the pressure shall be maintained for 60±1	flexure of substrate from the capacitance measured before the test.)
		sec.	150
		* Measurement to be made after keeping at room	15.50
		temp. for 24±2 hrs.	1 - 1 - 1 - 1 - 1 - 1 - 1 - 1 - 1 - 1 -
19.	Terminal Strength	* Pressurizing force :	* No remarkable damage or removal of the terminations.
	AEC-Q200-006	2N (0201 & 0402), 10N(0603), 18N(≥0805).	* Capacitance within the specified tolerance.
		* Test time: 60±1 sec.	* Q. value: NPO: Cap≥30pF, Q≥1000 ; Cap<30pF, Q≥400+20C.
20	Basm Lacd Tool	* Brook strength test PASSIVE SYSTEM	The label result of fallowing force
20	Beam Load Test AEC-Q200-003	* Break strength test * Beam speed: 2.5±0.25 mm/sec	The chip endure following force * Chip length ≤2.5mm: Thickness >0.5mm (20N), ≤0.5mm (8N)
	AEC-Q200-003	Beam speed. 2.5±0.25 mm/sec	* Chip length ≥3.2mm; Thickness ≥1.25mm (54.5N), <1.25mm (15N)
		OH CH	Only length 23.2mm, 1 llowiess 21.25mm (34.3m), <1.25mm (13m)
21	ESR	The ESR should be measured at room temperature	0402
		and tested at frequency 1±0.1 GHz.	0.1pF≤Cap≤1pF:< 350mΩ/pF
		FCHNOLOGY COR	1pF <cap≤5pf:< 300mω<="" th=""></cap≤5pf:<>
		AMOTORA COL	5pF <cap≤100pf:< 250mω<="" th=""></cap≤100pf:<>
			1

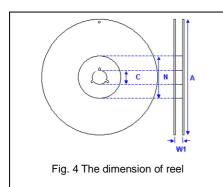
APPENDIXES

■ Tape & reel dimensions



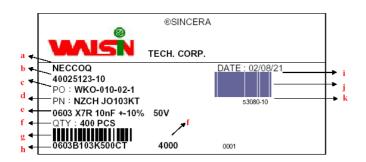


Size	0201	0402	0603		0805			1206			1210	
Thickness	L	N,E	S,H,X	A,H	В,Т	D,I	В,Т	C,J,D	G,P	Т	C,D,G,K	М
A ₀	0.40 +/-0.10	0.70 +/-0.20	1.05 +/-0.30	1.50 +/-0.20	1.50 +/-0.20	< 1.80	1.90 +/-0.50	< 2.00	<2.30	< 3.05	< 3.05	< 3.20
B ₀	0.70 +/-0.10	1.20 +/-0.20	1.80 +/-0.30	2.30 +/-0.20	-2.30 +/-0.20	< 2.70	3.50 +/-0.50	< 3.70	< 4.00	< 3.80	< 3.80	<4.00
Т	≦0.55	≦0.80	≦1.20	\$1.15	≦1.20	0.23 +/-0.1	≦1.20	0.23 +/-0.1	0.23 +/-0.1	0.23 +/-0.1	0.23 +/-0.1	0.23 +/-0.1
K ₀	-	-	-/14		5股	< 2.50	X	< 2.50	< 2.50	< 1.50	< 2.50	< 3.20
W	8.00	8.00	8.00	8.00	8.00	8.00	8.00	8.00	8.00	8.00	8.00	8.00
	+/-0.30	+/-0.30	+/-0.30	+/-0.30	+/-0.30	+/-0.30	+/-0.30	+/-0.30	+/-0.30	+/-0.30	+/-0.30	+/-0.30
P ₀	4.00	4.00	4.00	4.00	4.00	4.00	4.00	4.00	4.00	4.00	4.00	4.00
	+/-0.10	+/-0.10	+/-0.10	+/-0.10	+/-0.10	+/-0.10	+/-0.10	+/-0.10	+/-0.10	+/-0.10	+/-0.10	+/-0.10
10xP₀	40.00	40.00	40.00	40.00	40.00	40.00	40.00	40.00	40.00	40.00	40.00	40.00
	+/-0.10	+/-0.10	+/-0.20	+/-0.20	+/-0.20	+/-0.20	+/-0.20	+/-0.20	+/-0.20	+/-0.20	+/-0.20	+/-0.20
P ₁	2.00	2.00	4.00	4.00	4.00	4.00	4.00	4.00	4.00	4.00	4.00	4.00
	+/-0.05	+/-0.05	+/-0.10	+/-0.10	+/-0.10	+/-0.10	+/-0.10	+/-0.10	+/-0.10	+/-0.10	+/-0.10	+/-0.10
P ₂	2.00	2.00	2.00	2.00	2.00	2.00	2.00	2.00	2.00	2.00	2.00	2.00
	+/-0.05	+/-0.05	+/-0.05	+/-0.05	+/-0.05	+/-0.05	+/-0.05	+/-0.05	+/-0.05	+/-0.05	+/-0.05	+/-0.05
D ₀	1.50	1.50	1.50	1.50	1.50	1.50	1.50	1.50	1.50	1.50	1.50	1.50
	+0.1/-0	+0.1/-0	+0.1/-0	+0.1/-0	+0.1/-0	+0.1/-0	+0.1/-0	+0.1/-0	+0.1/-0	+0.1/-0	+0.1/-0	+0.1/-0
D ₁	-	-	1	%	-	1.00 +/-0.10	(*)	1.00 +/-0.10	1.00 +/-0.10	1.00 +/-0.10	1.00 +/-0.10	1.00 +/-0.10
E	1.75	1.75	1.75	1.75	1.75	1.75	1.75	1.75	1.75	1.75	1.75	1.75
	+/-0.10	+/-0.10	+/-0.10	+/-0.10	+/-0.10	+/-0.10	+/-0.10	+/-0.10	+/-0.10	+/-0.10	+/-0.10	+/-0.10
F	3.50	3.50	3.50	3.50	3.50	3.50	3.50	3.50	3.50	3.50	3.50	3.50
	+/-0.05	+/-0.05	+/-0.05	+/-0.05	+/-0.05	+/-0.05	+/-0.05	+/-0.05	+/-0.05	+/-0.05	+/-0.05	+/-0.05



Size	0201, 0402, 0603, 0805, 1206, 1210				
Reel size	7"	10"	13"		
С	13.0+0.5/-0.2	13.0+0.5/-0.2	13.0+0.5/-0.2		
W ₁	8.4+1.5/-0	8.4+1.5/-0	8.4+1.5/-0		
Α	178.0±1.0	250.0±1.0	330.0±1.0		
N	60.0+1.0/-0	100.0±1.0	100±1.0		

Example of customer label

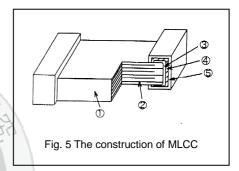


^{*}Customized label is available upon request.

- a. Customer name
- b. WTC order series and item number
- c. Customer P/O
- d. Customer P/N
- e. Description of product
- f. Quantity
- g. Bar code including quantity & WTC P/N or customer
- h. WTC P/N
- i. Shipping date
- j. Order bar code including series and item numbers
- k. Serial number of label

Constructions

No.	Nan	пе	NP0
1	Ceramic r	material	Hi-Q dielectric ceramic
2	Inner ele	ctrode	THE FIT CHI
3		Inner layer	Cu + Conductive Resin
4	Termination	Middle layer	Ni
(5)		Outer layer	Sn (Matt)



Storage and handling conditions

- (1) To store products at 5 to 40°C ambient temperature and 20 to 70%, related humidity conditions.
- (2) The product is recommended to be used within one year after shipment. Check solderability in case of shelf life extension is needed.

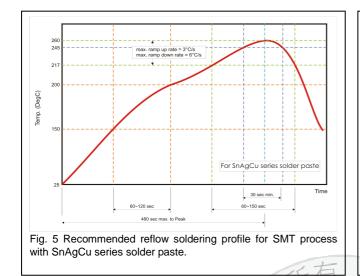
Cautions:

- a. The corrosive gas reacts on the terminal electrodes of capacitors, and results in the poor solderability. Do not store the capacitors in the ambience of corrosive gas (e.g., hydrogen sulfide, sulfur dioxide, chlorine, ammonia gas etc.)
- b. In corrosive atmosphere, solderability might be degraded, and silver migration might occur to cause low reliability.
- c. Due to the dewing by rapid humidity change, or the photochemical change of the terminal electrode by direct sunlight, the solderability and electrical performance may deteriorate. Do not store capacitors under direct sunlight or dewing condition. To store products on the shelf and avoid exposure to moisture.



Recommended soldering conditions

The lead-free termination MLCCs are not only to be used on SMT against lead-free solder paste, but also suitable against lead-containing solder paste. If the optimized solder joint is requested, increasing soldering time, temperature and concentration of N_2 within oven are recommended.



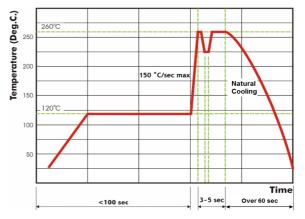


Fig. 6 Recommended wave soldering profile for SMT process with SnAgCu series solder.



served.

单击下面可查看定价,库存,交付和生命周期等信息

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